

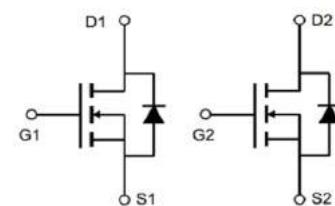
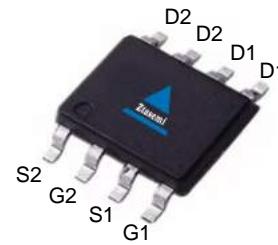


Features

- Dual N-Channel
- Green Device Available
- Low Gate Charge
- 100% EAS Tested

V_{DS}	60	V
$R_{DS(on),TYP}$ @ $V_{GS}=10$ V	10	mΩ
$R_{DS(on),TYP}$ @ $V_{GS}=4.5$ V	14	mΩ
I_D	13	A

SOP-8



Part ID	Package Type	Marking	Packing
ZTG11D06S	SOP-8	ZTG11D06S	4000pcs/reel

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings ($T_c=25^\circ\text{C}$ Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	± 20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	60	V	
T_J	Maximum Junction Temperature	150	°C	
T_{STG}	Storage Temperature Range	-55 to 150	°C	
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 2)	$T_c=25^\circ\text{C}$	50	A
Mounted on Large Heat Sink				
I_D	(Note 1) Drain Current-Continuous	$T_c=25^\circ\text{C}$	13	A
		$T_c=100^\circ\text{C}$	8.8	A
P_D	Maximum Power Dissipation (Note 4)	3.1	W	
$R_{\theta JA}$	Thermal Resistance Junction-Ambient (Note 1)	40.3	°C/W	
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed (Note 3)	64.8	mJ	



Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J=25^\circ\text{C}$ (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	60	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}, V_{GS}=0\text{V}$	--	--	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	± 100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.4	1.9	2.4	V
$R_{DS(\text{on})}$	Drain-Source On-State Resistance (Note 4)	$V_{GS}=10\text{V}, I_D=13.5\text{A}$	--	10	13	$\text{m}\Omega$
$R_{DS(\text{on})}$	Drain-Source On-State Resistance	$V_{GS}=4.5\text{V}, I_D=11.5\text{A}$	--	14	18	$\text{m}\Omega$

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

C _{iss}	Input Capacitance	$V_{DS}=30\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	1055	--	pF
C _{oss}	Output Capacitance		--	422	--	pF
C _{rss}	Reverse Transfer Capacitance		--	21	--	pF
R _g	Gate Resistance	f=1MHz	--	1.4	--	Ω
Q _g	Total Gate Charge	$V_{DS}=30\text{V}, I_D=13\text{A}, V_{GS}=10\text{V}$	--	18.2	--	nC
Q _{gs}	Gate-Source Charge		--	6.5	--	nC
Q _{gd}	Gate-Drain Charge		--	3.8	--	nC

Switching Characteristics

T _{d(on)}	Turn-on Delay Time	$V_{DD}=30\text{V}, I_D = 13\text{A}, R_G=3.0\Omega, V_{GS}=10\text{V}$	--	6.9	--	ns
T _r	Turn-on Rise Time		--	52.1	--	ns
T _{d(off)}	Turn-Off Delay Time		--	17.6	--	ns
T _f	Turn-Off Fall Time		--	7.8	--	ns

Source- Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

I _S	Diode Forward Current (Note 1,5)		--	--	13	A
V _{SD}	Forward on voltage (Note 2)	$I_S=1\text{A}, V_{GS}=0\text{V}$	--	--	1.2	V

Notes:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{DD}=50\text{V}, V_{GS}=10\text{V}, L=0.4\text{mH}, I_{AS}=18\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

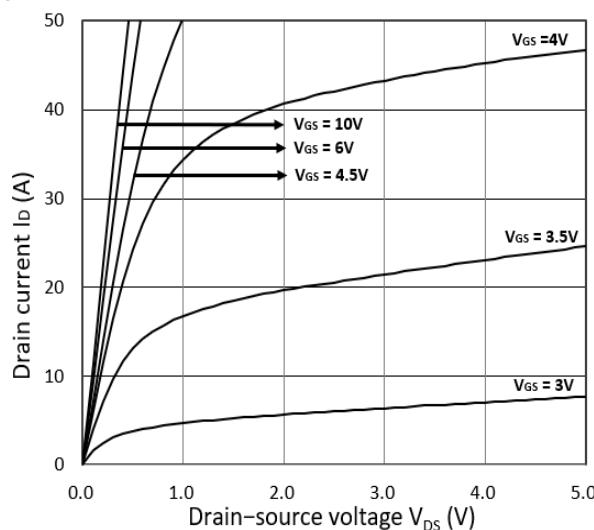


Figure 1. Output Characteristics

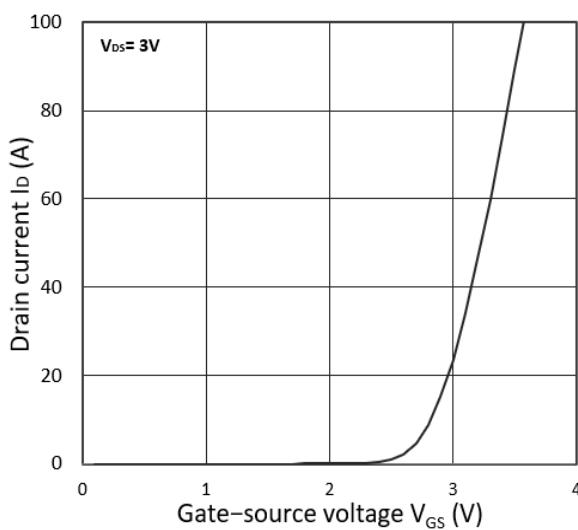


Figure 4. Transfer Characteristics

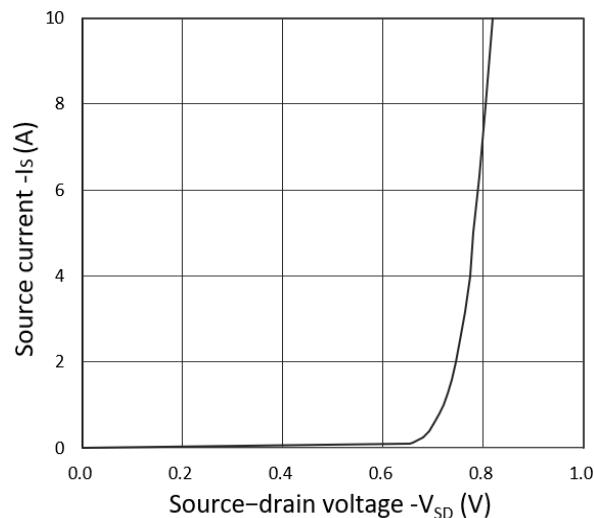


Figure 2. Forward Characteristics of Reverse

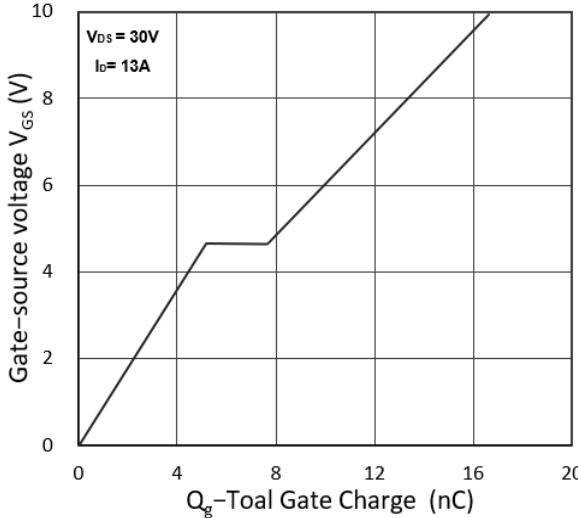


Figure 5. Gate Charge Characteristics

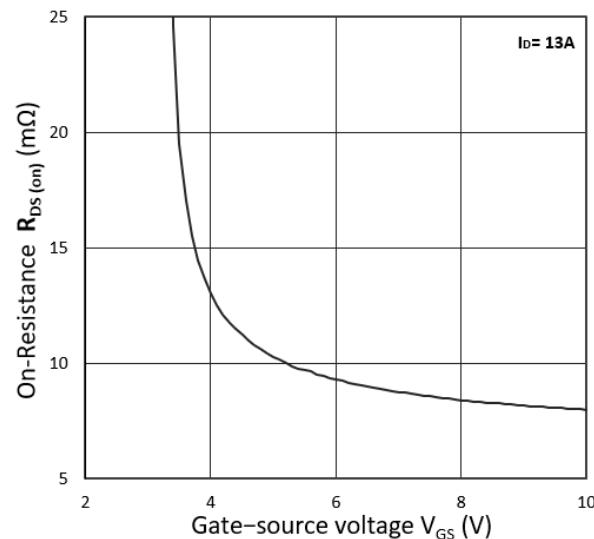


Figure 3. $R_{DS(on)}$ vs. V_{GS}

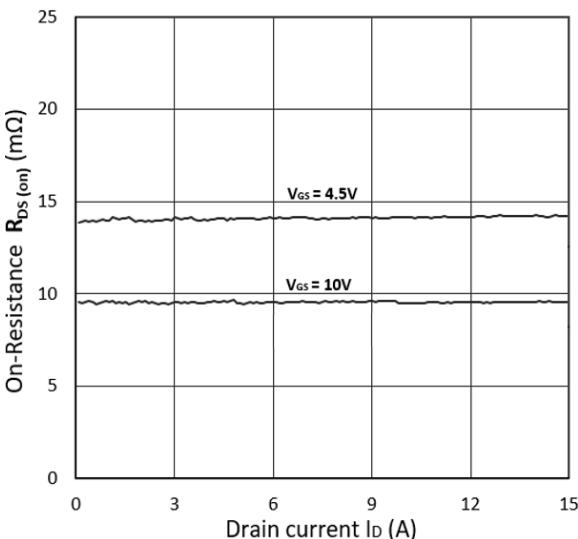


Figure 6. $R_{DS(on)}$ vs. I_D

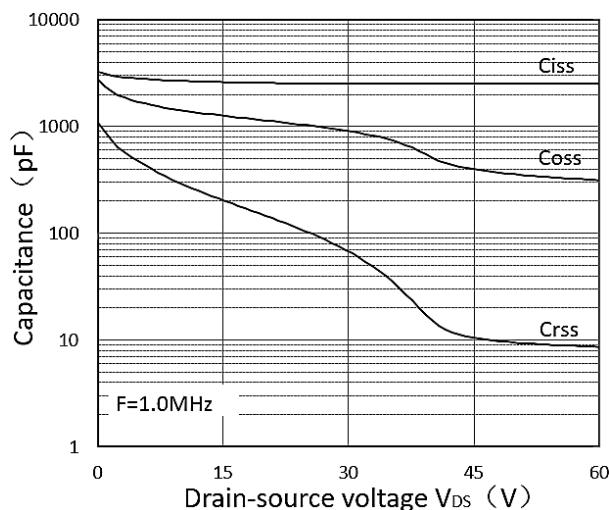


Figure 7. Capacitance Characteristics

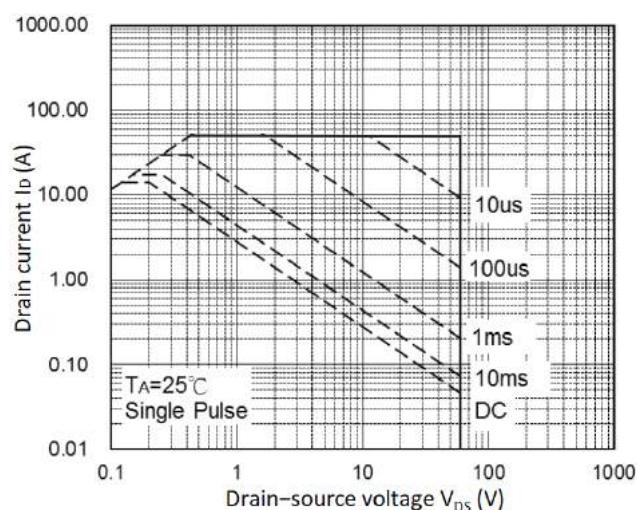


Figure 8. Safe Operating Area

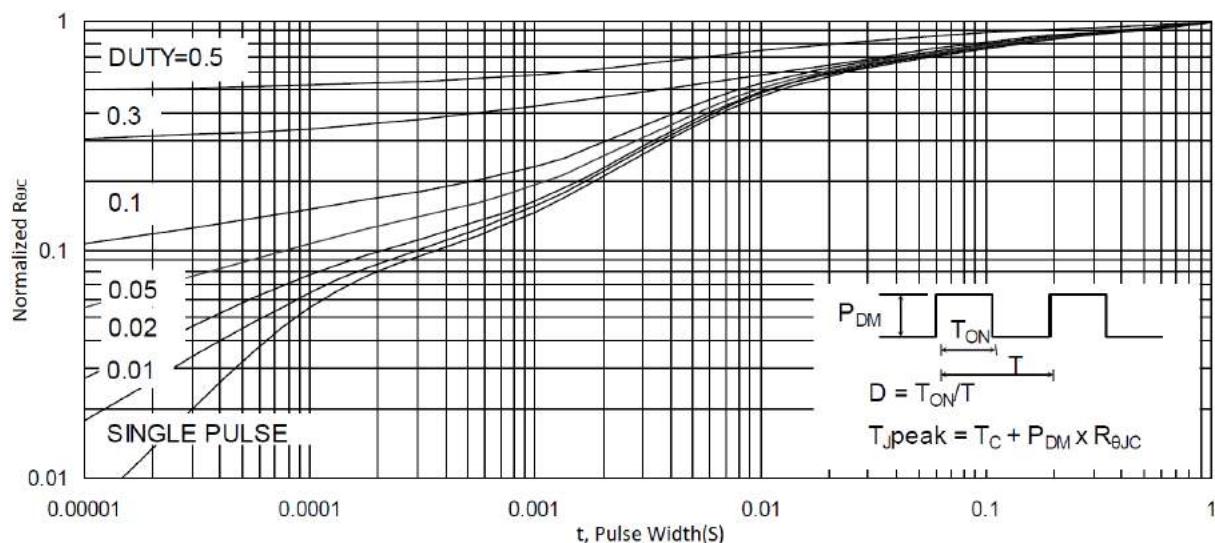


Figure 9. Normalized Maximum Transient Thermal Impedance

Test Circuit

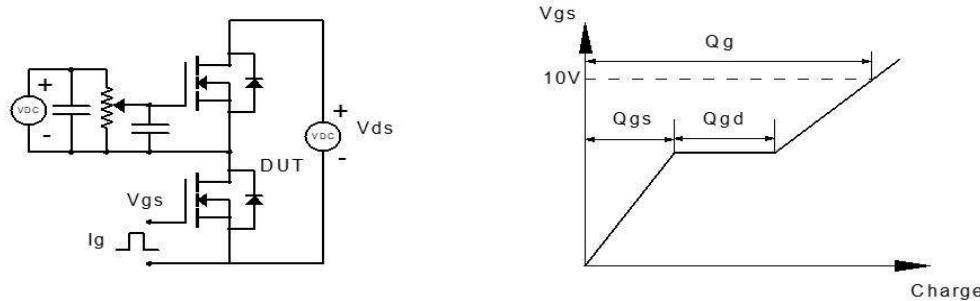


Figure 1: Gate Charge Test Circuit & Waveform

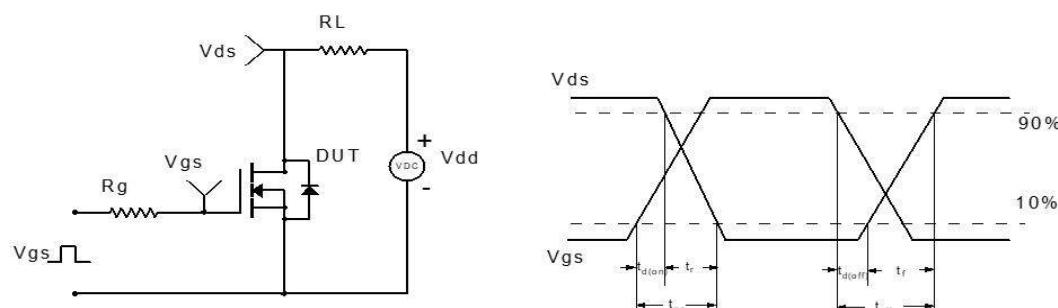


Figure 2: Resistive Switching Test Circuit & Waveform

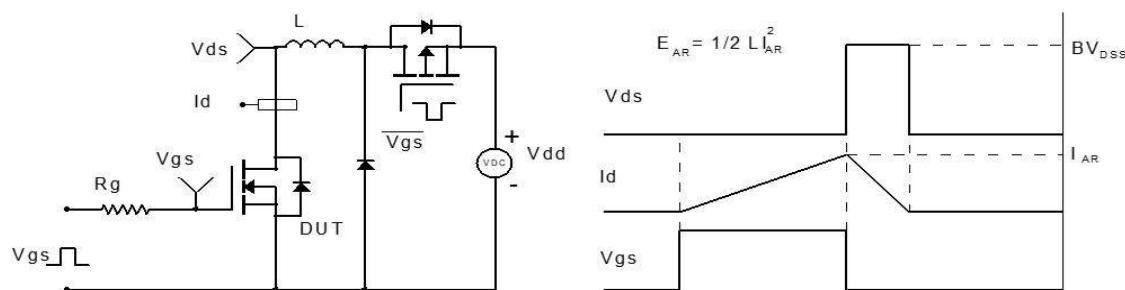


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

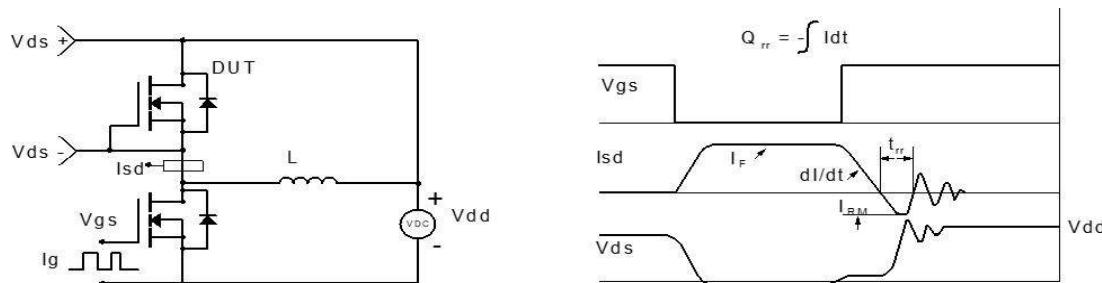
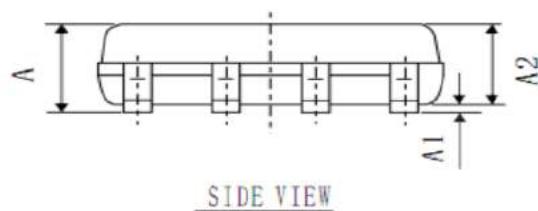
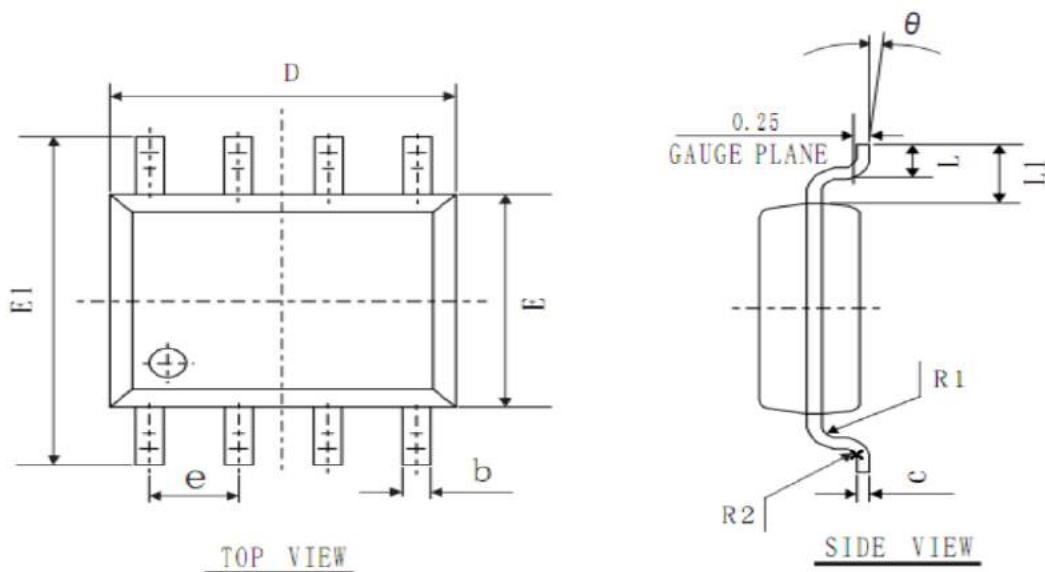


Figure 4: Diode Recovery Test Circuit & Waveform



SOP-8 Package Information



COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	1.40	1.60	1.80
A1	0.05	0.15	0.25
A2	1.35	1.45	1.55
b	0.30	0.40	0.50
c	0.153	0.203	0.253
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
L	0.45	0.70	1.00
θ	2°	4°	6°
L1	1.04 REF		
e	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		

Customer Service

Sales and Service:

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